



Material Content Data Sheet



Sales Product Name		IPB017N08N5		Issued		4. July 2019		
MA#		MA001192610						
Package		PG-TO263-3-2		Weight*		1562.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.046	0.45	0.45	4509	4509
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.46	19.49	194567	194820
	non noble metal	aluminium	7429-90-5	11.309	0.72	0.72	7238	7238
wire	non noble metal	aluminium	7429-90-5	11.309	0.72	0.72	7238	7238
encapsulation	organic material	carbon black	1333-86-4	10.131	0.65		6484	
	plastics	epoxy resin	-	111.446	7.13		71322	
	inorganic material	silicondioxide	60676-86-0	553.853	35.44	43.22	354447	432253
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6180	6180
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.122	0.01		78	
	noble metal	silver	7440-22-4	0.153	0.01		98	
	non noble metal	lead	7439-92-1	5.834	0.37	0.39	3733	3909
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.05	35.10	350488	350944
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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